

Abstract of the Disclosure:

A module serves as a heat sink for semiconductor components.  
The module includes a diamond/composite substrate that carries  
a multilayer coating on at least one substrate surface and a  
5 housing frame made from ceramics which is soldered onto the  
substrate. The module excellently fulfills the demands imposed  
on it, namely a good ability for areally joining to the  
semiconductor component, a high heat transfer through the  
joining zone and a good electrical conductivity of the module  
10 in the joining zone.

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